

Title (en)  
FORMING METHOD FOR ELIMINATING SEPARATOR DISTORTION AND FORMING DEVICE FOR ELIMINATING SEPARATOR DISTORTION

Title (de)  
VERFAHREN ZUR BESEITIGUNG VON SEPARATORVERZERRUNG UND FORMVORRICHTUNG ZUR BESEITIGUNG VON SEPARATORVERZERRUNG

Title (fr)  
PROCÉDÉ DE FORMATION POUR UNE ÉLIMINATION DE DISTORSION DE SÉPARATEUR ET DISPOSITIF DE FORMATION POUR UNE ÉLIMINATION DE DISTORSION DE SÉPARATEUR

Publication  
**EP 3007260 A1 20160413 (EN)**

Application  
**EP 14808234 A 20140417**

Priority  
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• JP 2014060984 W 20140417

Abstract (en)  
[Problem] To provide a molding method for removing distortion in a separator, by which it is possible to remove distortion and mold a separator with high accuracy. [Solution] This molding method for removing distortion in a separator 51 is a method for removing distortion in a molding part 50b of a pre-molded separator base material 50. In this molding method there are employed a first die 11 which corresponds to a product shape of a first molding surface 50b1 pre-molded onto a first surface of a separator base material, and second dies 21 which are opposed to the first die and which correspond to a product shape of a second molding surface 50b2 pre-molded onto the other surface opposite the first surface of the separator base material. The molding method has a first molding step and a second molding step. In the first molding step, the first die is pressed by applying an impact force towards the first molding surface side of the separator base material, causing the separator base material to move towards the second dies. In the second molding step which follows the first molding step, the second dies are pressed towards the second molding surface side of the separator base material, and the molding part of the separator base material is sandwiched between the first die and the second dies.

IPC 8 full level  
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